

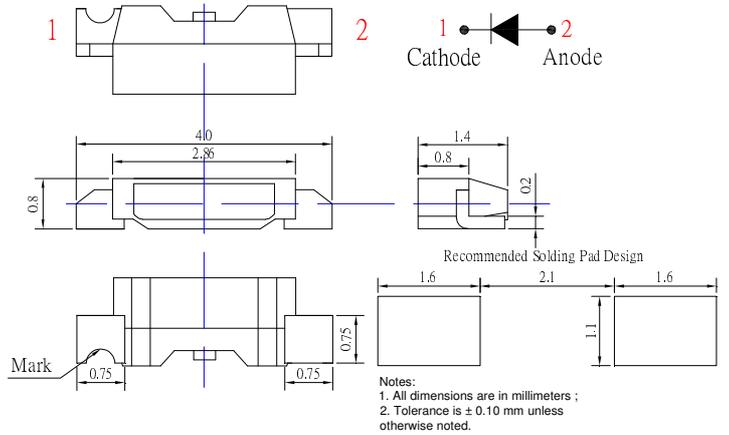
■Features

- Single chip
- Suitable for all SMT assembly methods.
- Sorting for I_v and V_f @ 20mA of I_f
- Compact package outline
(LxWxT) of 4.0mm x 0.8mm x 1.4mm
- Compatible to IR reflow soldering.
- MSL:5a

■Applications

- Mobile communications equipment (Ipad, Iphone, etc.)
- Digital products (MP3,MP4, etc.)

■Outline Dimension

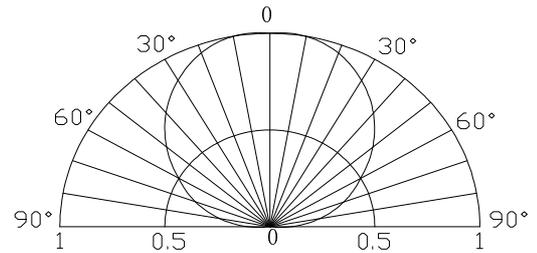


■Absolute Maximum Rating (Ta=25°C)

Item	Symbol	Value		Unit
		W/M/K/PG//B	YG/Y/R	
DC Forward Current	I_F	30	30	mA
Pulse Forward Current*	I_{FP}	100	100	mA
Reverse Voltage	V_R	5	5	V
Power Dissipation	P_D	102	72	mW
Operating Temperature	T_{opr}	-30 ~ +85		°C
Storage Temperature	T_{stg}	-40~ +100		°C
Lead Soldering Temperature	T_{sol}	260°C/10sec		-

*Pulse width Max.10ms Duty ratio max 1/10

■Directivity



■Electrical -Optical Characteristics (Ta=25°C)

Part Number	Color		V_F (V)			I_R (μ A)	I_v (mcd)			CCT(K)\Wd(nm)*			2 θ 1/2(deg)	
			Min.	Typ.	Max.		Max.	Min.	Typ.	Max.	Min.	Typ.		Max.
			$I_F=20$ mA				$V_R=5$ V	$I_F=20$ mA						
OSW44008C1F	White	W	2.8	3.0	3.4	10	1400	2000	-	CCT:5500~8500K			120	
OSW54008C1F	Cool White	W	2.8	3.0	3.4	10	1400	2000	-	CCT:8000~18000K			120	
OSM44008C1F	Warm White	M	2.8	3.0	3.4	10	1400	2000	-	CCT:2300~2700K			120	
OSK54008C1F	Pink	K	2.8	3.0	3.4	10	100	200	-	typ.:X=0.26,Y=0.12			120	
OSB54008C1F	Blue	B	2.8	3.0	3.4	10	200	400	-	460	465	470	120	
OSG84008C1F	Yellow Green	YG	1.8	2.0	2.4	10	70	120	-	565	570	575	120	
OSG54008C1F	Pure Green	PG	2.8	3.0	3.4	10	800	1500	-	515	520	525	120	
OSY54008C1F	Yellow	Y	1.8	2.0	2.4	10	200	400	-	585	590	595	120	
OSR54008C1F	Red	R	1.8	2.0	2.4	10	200	400	-	620	625	630	120	

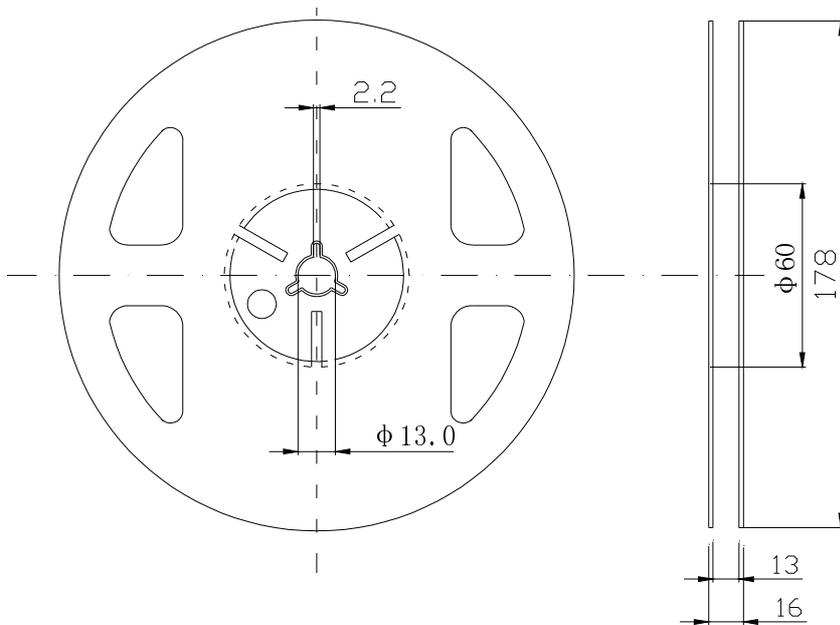
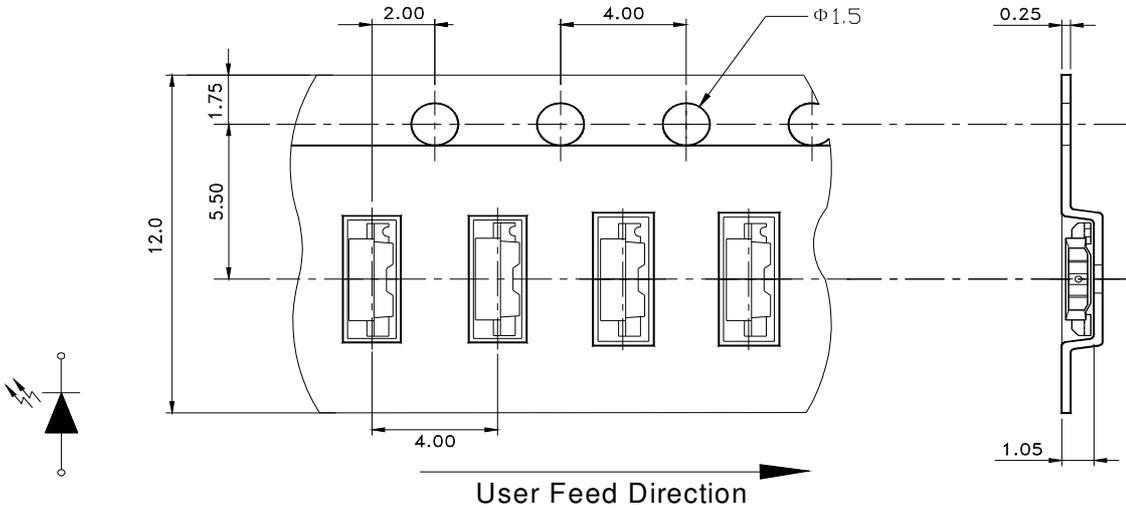
*1 Tolerance of measurements of chromaticity coordinate is $\pm 10\%$

*2 Tolerance of measurements of dominant wavelength is ± 1 nm

*3 Tolerance of measurements of luminous intensity is $\pm 15\%$

*4 Tolerance of measurements of forward voltage is ± 0.1 V

PACKING DIMENTIONS



Notes:

1. Unit: mm
2. 3000pcs/Reel

Precautions in Use for Surface Mount Diode

■ Storage

· Storage Conditions

Before opening the package:

The LEDs should be kept at 30°C or less and 60%RH or less. The LEDs should be used within a year. When storing the LEDs, moisture proof packaging with absorbent material (silica gel) is recommended.

· After opening the package:

Soldering should be done right after opening the package (within 24hrs).

Keeping of a fraction, sealing and Temperature: 5~30°C Humidity: Less than 30%.

If the package has been opened more than 24 Hours, components should be dried for 12hrs, at 60±5°C.

· Optosupply LED electrode sections are comprised of a silver plated copper alloy. The silver surface may be affected by environments which contain corrosive gases and so on. Please avoid conditions which may cause the LED to corrode, tarnish or discolor. This corrosion or discoloration may cause difficulty during soldering operations. It is recommended that the User use the LEDs as soon as possible.

· Please avoid rapid transitions in ambient temperature, especially in high humidity environments where condensation can occur.